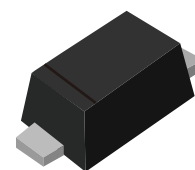


FEATURES

- Small Surface Mounting Type
- Low Reverse Current And Low Forward Voltage
- High Reliability



SOD-523



Marking



Schematic Symbol

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	40	V
DC Reverse Voltage	V_R	40	V
Mean Rectifying Current	I_O	30	mA
Non-Repetitive Peak Forward Surge Current@t=8.3ms	I_{FSM}	200	mA
Power Dissipation	P_D	150	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	667	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	-40~+125	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Reverse voltage	$V_{(BR)}$	$I_R=1\text{mA}$	40			V
Forward Voltage	V_F	$I_F=1\text{mA}$	0.20		0.37	V
Reverse Current	I_R	$V_R=30\text{V}$	0.01		0.5	μA
Capacitance Between Terminals	C_T	$V_R=1\text{V}, f=1\text{MHz}$	0.5	2	10	pF

CHARACTERISTIC CURVES

Fig.1 Forward Characteristics

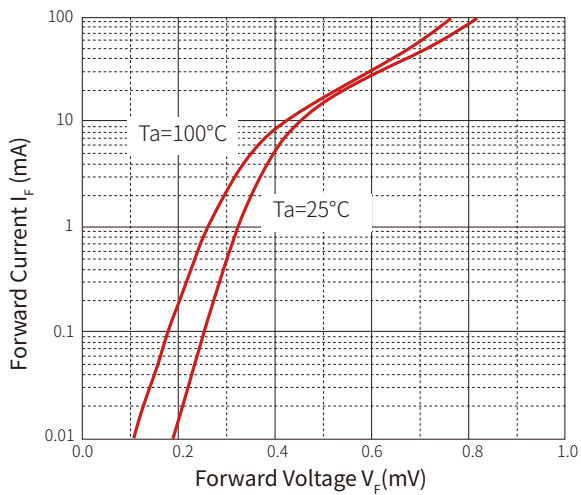


Fig.2 Reverse Characteristics

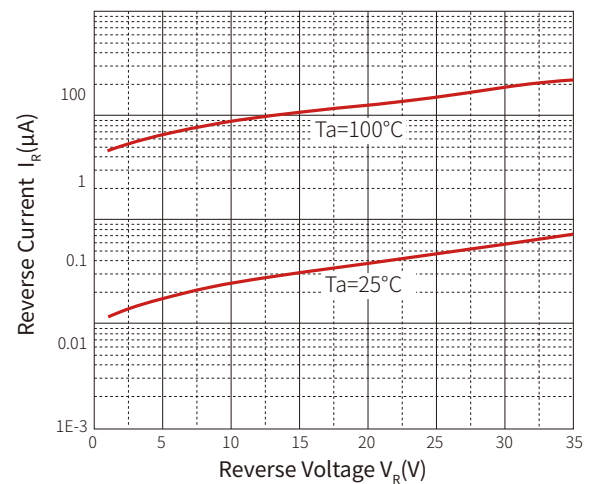
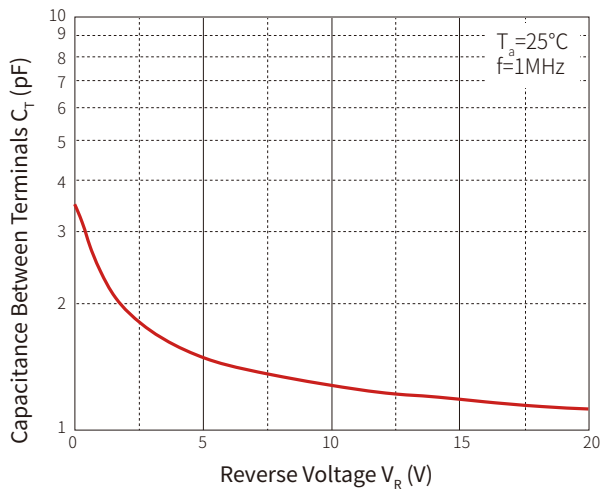
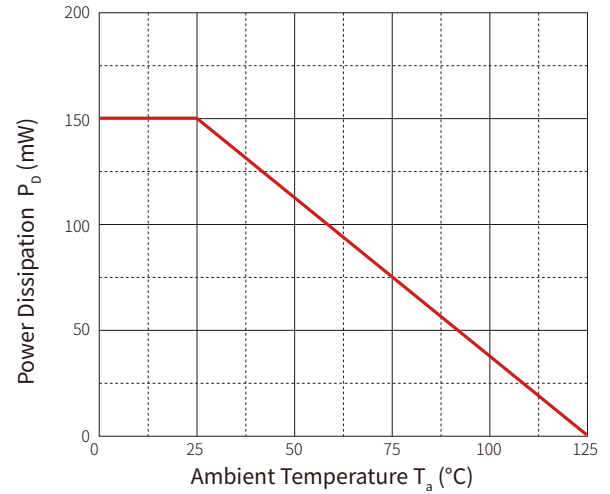
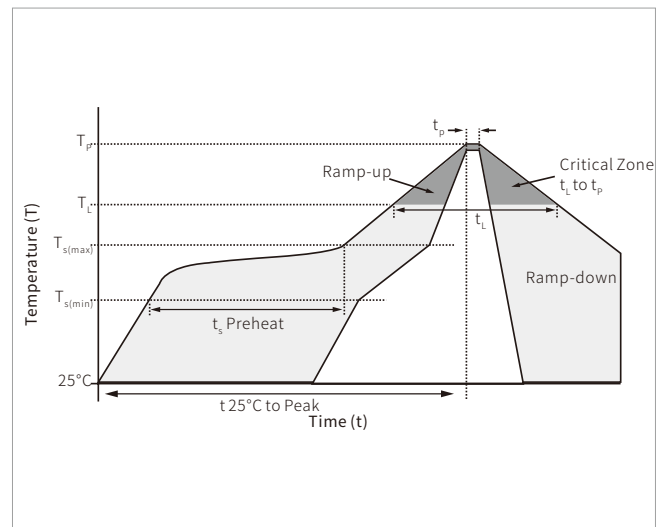


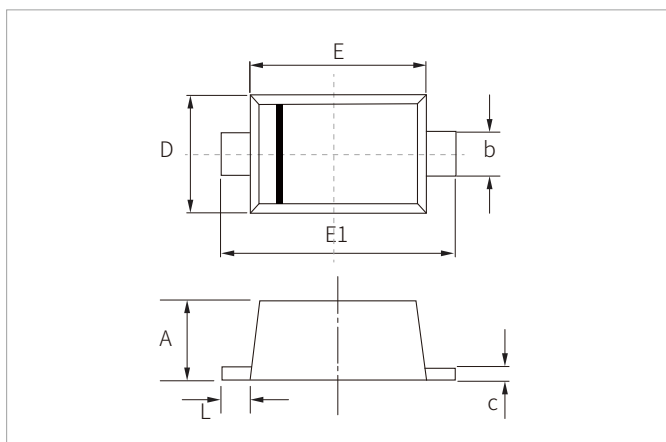
Fig.3 Capacitance Characteristics

Fig.4 Power Derating Curve


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(\min)}$)	150 $^\circ\text{C}$
	Temperature Max ($T_{s(\max)}$)	200 $^\circ\text{C}$
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3 $^\circ\text{C}/\text{second}$ max
$T_{s(\max)}$ to T_L - Ramp-up Rate		3 $^\circ\text{C}/\text{second}$ max
Reflow	Temperature (T_L) (Liquidus)	217 $^\circ\text{C}$
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 $^\circ\text{C}$
Time within 5 $^\circ\text{C}$ of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6 $^\circ\text{C}/\text{second}$ max
Time 25 $^\circ\text{C}$ to peak Temperature (T_p)		8 minutes max.
Do not exceed		260 $^\circ\text{C}$

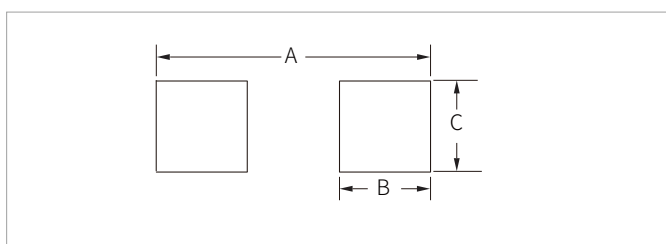


SOD-523 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.80	0.020	0.031
b	0.25	0.35	0.010	0.014
c	0.07	0.20	0.003	0.008
D	0.70	0.90	0.028	0.035
E	1.10	1.30	0.043	0.051
E1	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	Min.	Min.
A	2.00	0.0787
B	0.60	0.0236
C	0.70	0.0276

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
RB751S-40	SOD-523	3000PCS	7"

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By QR Code

Website



Wechat

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